

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
WASHINGTON, D.C. 20231**

Inventor: **My Nguyen, et al.**

Serial No: **Div. of 09/851103**

Filed: **May 7, 2001**

For: **Interface Materials and
Methods of Production and
Use Thereof**

Examiner:

Art Unit:

PRELIMINARY AMENDMENT

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Please enter the following preliminary amendment:

IN THE CLAIMS

Please cancel claims (1-40) and add the following claims addressing subject matter in application serial number 09/851103:

41. (New) An interface material for electronic devices comprising at least one resin material and at least one solder material comprising indium, silver, copper, aluminum, tin, bismuth, gallium and alloys thereof, silver-coated copper, silver-coated aluminum and combinations thereof.
42. (New) The interface material of claim 41, wherein the interface material comprises at least about 50 weight percent of the at least one solder material.